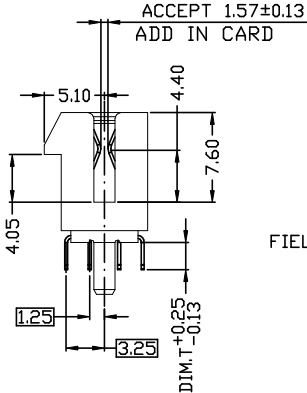


REV.	ECN. NO.	APPD.
A	BC-13-0084698	Johnny Tang

NOTES:

- ELECTRICAL CHARACTERISTICS:
 - 1-1 CURRENT RATING: 1.1 A MIN., 30°C RISE ABOVE AMBIENT.
 - 1-2 CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL, 50 MILLIOHMS MAX. AFTER TEST.
 - 1-3 INSULATION RESISTANCE: 1000 MEGOHMS MIN.
 - 1-4 DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL
- MECHANICAL CHARACTERISTICS:
 - 2-1 CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
 - 2-2 CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
 - 2-3 DURABILITY: 50 MATING AND UNMATING CYCLES.
 - 2-4 CONTACT RETENTION FORCE: 4.9 N MIN.
- ENVIRONMENTAL CHARACTERISTICS:
 - 3-1 OPERATING TEMPERATURE RANGE: -40°C TO +105°C .
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCTION DETAILS & AVAILABILITY



PROD. NO.: 2EG 0 ** * * - DPDB- **

FIELD PRODUCT SERIES: 2EG= PCI EXPRESS

TERMINAL TYPE: 0= VERTICAL TYPE

NO. OF POS. 18= 36 POSITIONS, 32= 64 POSITIONS, 49= 98 POSITIONS, 82= 164 POSITIONS

PLATING TYPE: DF: LEAD FREE, RoHS COMPLIANT, DH: LEAD FREE & HALOGEN FREE

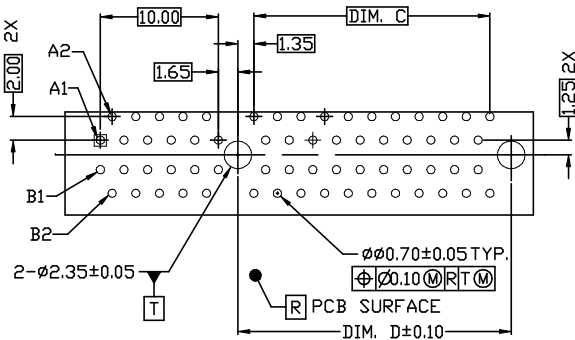
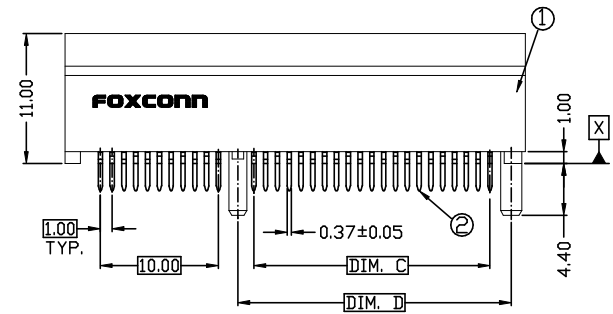
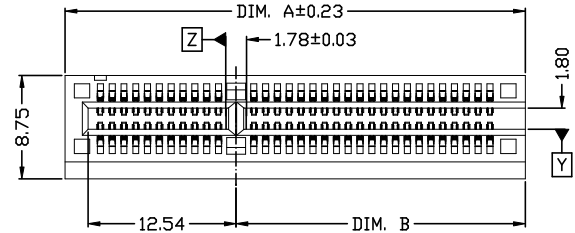
EXTENSION CODE

CONTACT AREA GOLD PLATING: 1= GOLD FLASH, 7= 15u" GOLD, 3= 30u" GOLD

TAIL LENGTH: 1= 2.30mm, 2= 3.10mm

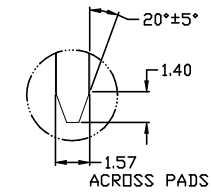
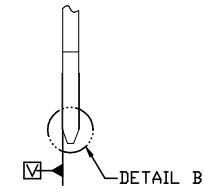
2EG0**2*-DPDB-**	3.10
2EG0**1*-DPDB-**	2.30
PRODUCT NUMBER	DIM. T

2	CONTACT	COPPER ALLOY	50u" MIN. NICKEL PLATING OVERALL UNDERPLATED, 100u" MIN. TIN PLATING OVER NICKEL AT TAIL, GOLD PLATING ON CONTACT AREA.	
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLDED BLACK	
ITEM	DESCRIPTION	MATERIAL	TREATMENT	
X.±	X.±	UNITS mm	NAME<INTENDED USE>	FOXCONN
X± 0.38	X.±	MAT'L	PCI-Express WITH OPEN END	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX± 0.25	.XX*±	N/A	PART NO.<INTENDED USE>	CLASS: □CONFIDENTIAL□SECRET ■GENERAL
.XXX±	.XXX*±	FINISH	2EG0****-DPDB-**	TITLE:PCI EXPRESS CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: Johnny Tang 12/02/13	DVG. NO.: 303-0000-3075
Q'TY			CHKD: Arthur Niu 12/02/13	SCALE SHEET REV.
DR: Y-Y Bao 12/02/13			DR: Y-Y Bao 12/02/13	N/A 1/2 A

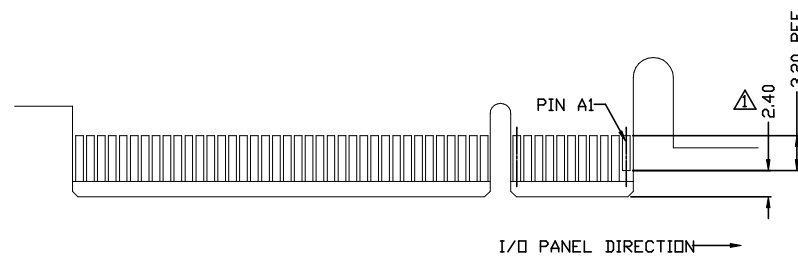


RECOMMENDED PCB LAYOUT

2EG082**-DPDB-**-	89.00	74.15	70.00	73.15
2EG018**-DPDB-**-	25.00	10.50	6.00	9.15
2EG049**-DPDB-**-	56.00	41.50	37.00	40.15
2EG032**-DPDB-**-	39.00	24.50	20.00	23.15
PRODUCT NUMBER	DIM. A	DIM. B	DIM. C	DIM. D



SECONDARY (SOLDER) SIDE



CONNECTOR LINK WIDTH	# POS REF	N	DIM. E	DIM. G	'C'
X1	36	6	6.00	8.15	B17
X4	64	20	20.00	22.15	B31
X8	98	37	37.00	39.15	B48
X16	164	70	70.00	72.15	B81

1. NO TIE PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND 'C'.

2. CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

X±	X.±	UNITS mm	NAME(INTENDED USE)	FOXCONN FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			
X±	X.±	MAT'L	PCI-Express WITH OPEN END				
XX± 0.13	XX±	N/A	PART NO.(INTENDED USE)	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL			
XXX±	XXX±	FINISH	2EG0***-DPDB-***	TITLE:PCI EXPRESS CUSTOMER DRAWING			
		N/A	APPD: Johnny Tang 12/02'13	DWG. NO.:			
				303-0000-3075			
		Q'TY	CHKD: Arthur Niu 12/02'13				
		N/A	DR: Y-Y Bao 12/02'13				
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					N/A	2/2	A